

Kiss-Cut Module – KCM-S

The Kiss-cut Module cuts self-adhesive vinyls and materials with a thickness of up to 1.5 mm. The high processing speed and the very high precision when cutting smaller contours are outstanding.

The KCM-S is a further development of the tried and tested C2 tool head. The low weight and short stroke movements promise very high processing speeds. The module also impresses through its simple operation, fast tool changing and very high precision. Depending on the intended use, there are two different processing modes that can be chosen:

In **pressure mode**, the module exerts a constant, very finely adjustable pressure of between 30-1600 grams on the processing material. Cover layers of self-adhesive vinyls are separated precisely without damaging the base material.

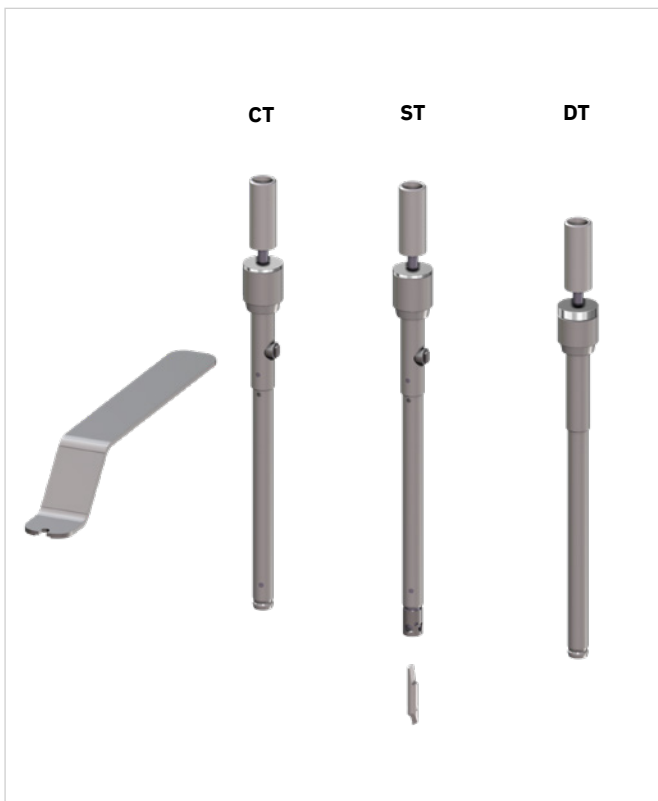
In **position mode**, the tool is lowered to the set depth and the material is cut through completely.

Two cutting tools and one drawing tool can be used in the KCM-S:

CT Universal cutting tool

ST Cutting tool with integrated, height-adjustable glide element

DT Drawing tool



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Details

Cutting depths

- Through-cutting: 1.5 mm
- Kiss-cut: 1.5 mm
- Kiss-cut with through-cutting: 1.8 mm

Pressure mode: 30-1500 g.

Weight: 1.7 kg.

Use of Zünd drag knives with round shaft (Z1, Z2, Z3, Z4, Z5, W6).

Working area restriction: X 5.5 mm, Y 6 mm.

The KCM-S is supported by the cutter firmware from V1.50.

Compatible with [S3](#).

Benefits at a glance

Kiss-cutting and through-cutting in one module.

Exact adjustment of optimal pressure using LED display.

Fast, uncomplicated tool changing.

Short stroke movement and light tools ensure a high processing speed.

Tangential positioning of the blade ensures perfect results with fine contours.